

**Product / Package Information**

Package	LFCSP - Sawn
Body Size (mm)	3 X 3 X 0.75 (2.34 X 1.60 EP)
Lead Count	8
Terminal Finish	100 Sn
MS Number	MS012694C

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes
Last Updated	07-Jun-19

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	7.22E-03	86.91	869100	35.56		355552
Thermosets	Epoxy & Phenol Resin	Proprietary	1.06E-03	12.78	127800	5.23		52283
Other inorganic materials	Carbon black	1333-86-4	2.57E-05	0.31	3100	0.13		1268
Subtotal			8.30 E-03	100.00	1000000	40.91		409103

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	9.72 E-03	97.5	975000	47.87		478651
Copper & its alloys	Iron	7439-89-6	2.34 E-04	2.35	23500	1.15		11537
Copper & its alloys	Zinc	7440-66-6	1.20 E-05	0.12	1200	0.06		589
Copper & its alloys	Phosphorus	7723-14-0	2.99 E-06	0.03	300	0.01		147
Subtotal			9.97 E-03	100.00	1000000	49.09		490924

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.49 E-05	100.0	1000000	0.12		1227

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	4.75 E-04	100.0	1000000	2.34		23377

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	4.70 E-05	100.0	1000000.00	0.23		2314

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	1.42 E-03	100.0	1000000	7.01		70132

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	4.61 E-05	77.71	777100	0.23		22771
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	1.84 E-06	3.11	31100	0.01		91
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	1.84 E-06	3.11	31100	0.01		91
Other organic materials	Butyrolactone, gamma-	96-48-0	1.84 E-06	3.11	31100	0.01		91
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	1.84 E-06	3.11	31100	0.01		91
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.84 E-06	3.11	31100	0.01		91
Other organic materials	Organosilane	TS ref# 10001	1.84 E-06	3.11	31100	0.01		91
Other inorganic materials	Copper(II) oxide	1317-38-0	1.84 E-06	3.11	31100	0.01		91
Other organic materials	Epoxy resin modifier	TS ref# 10038	3.08 E-07	0.52	5200	0.00		15
Subtotal			5.93 E-05	100.0	1000000	0.29		2922

Package Totals	Weight (g)	Percentage (%)	PPM
	2.03 E-02	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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